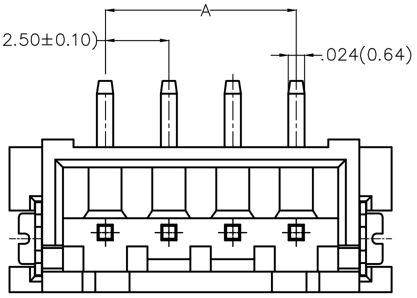
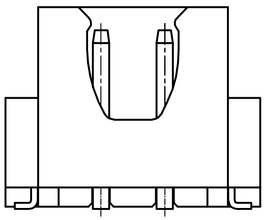
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1	⚠	Change the Packaging specification	15/MAR/24	KATE	LEO

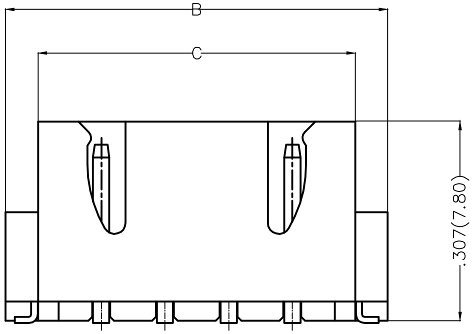


Electrical
Current Rating: 3.0A AC(rms)/DC
Voltage Rating: 250V AC(rms)/DC
Contact Resistance: 20 mΩ Max
Insulation Resistance: 1000 MΩ MIN
Withstanding Voltage: 1000V AC r.m.s
Temperature Range–Operating: –25℃～+85℃

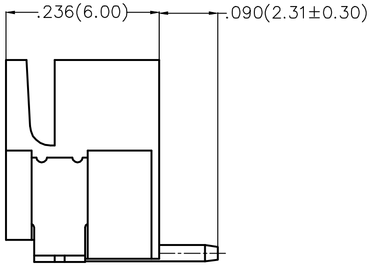
Material and Plating
Housing: PA9T(UL 94V–0)
Contact Pin: Brass
Plating: Tin Plated

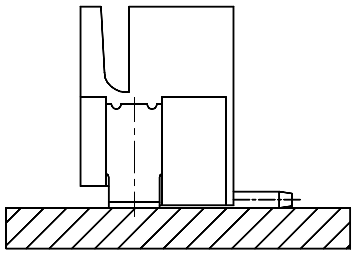


2Circuits



3–12Circuits



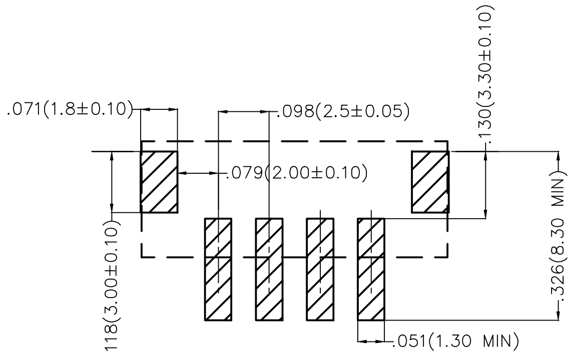


Assembly Layout

Ordering Information

FWF	250	28	—	S	XX	S	2	4	W5	M
1	2	3		4	5	6	7	8	9	10

1	Category	FWF–Wafer
2	Series Number	250–Pitch2.5mm
3	Distinction No.	28
4	Row Option	S–Single Row
5	Circuits	XX
6	Entry Angle	S–180° Vertical
7	Plating	2–Tin Plated
8	Material–Resin	4–PA9T
9	Color–Resin	W5–Natural
10	Packaging	M–Reel



Recommended P.C.Board Layout

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 01/AUG/13
DESIGN UNITS Inch (metric)	X.±.012(0.30)	X.°±5°	CHECKED BY CHERRY	DATE 01/AUG/13
SCALE 5:1 / SIZE A4	X.X±.008(0.20)	.X°±2°	DRAWN BY KEVIN	DATE 01/AUG/13
	X.XX±.006(0.15)	.XX°±1°		
	X.XXX±.004(0.10)	.XXX°±0.5°		

PART NO. FWF25028–SXXS24W5M	ITEM NO. FWF25028	TXGA Leader Of Industry
TITLE Wire to Board (Wafer) Pitch 2.5mm 180° Vertical (SMT)	REV 1	SHEET NO. 1/3

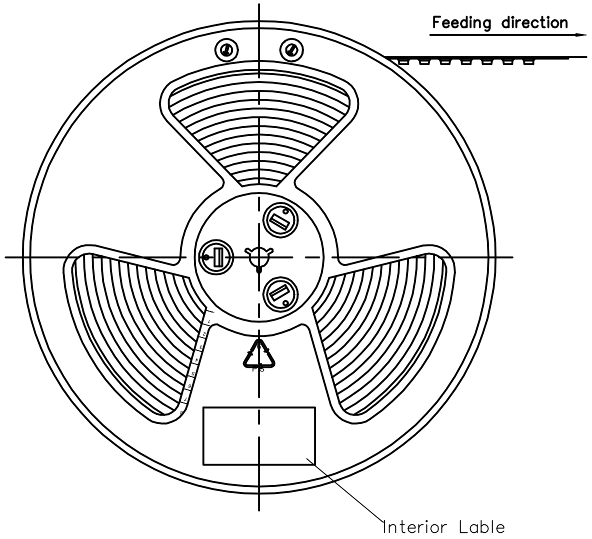
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

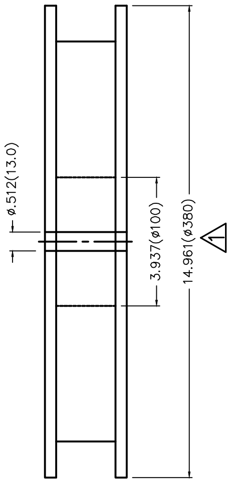
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

Circuits (n)	Part No.	Dimensions(in/mm)		
		A	B	C
2	FWF25028–S02S24W5M	.098(2.50)	.394(10.00)	.293(7.45)
3	FWF25028–S03S24W5M	.197(5.00)	.492(12.50)	.392(9.95)
4	FWF25028–S04S24W5M	.295(7.50)	.591(15.00)	.490(12.45)
5	FWF25028–S05S24W5M	.394(10.00)	.689(17.50)	.589(14.95)
6	FWF25028–S06S24W5M	.492(12.50)	.787(20.00)	.687(17.45)
7	FWF25028–S07S24W5M	.591(15.00)	.886(22.50)	.785(19.95)
8	FWF25028–S08S24W5M	.689(17.50)	.984(25.00)	.884(22.45)
9	FWF25028–S09S24W5M	.787(20.00)	1.083(27.50)	.982(24.95)
10	FWF25028–S10S24W5M	.886(22.50)	1.181(30.00)	1.081(27.45)
~~11~~	~~FWF25028–S11S24W5M~~	~~.984(25.00)~~	~~1.024(32.50)~~	~~1.179(29.95)~~
~~12~~	~~FWF25028–S12S24W5M~~	~~1.083(27.50)~~	~~1.378(35.00)~~	~~1.278(32.45)~~

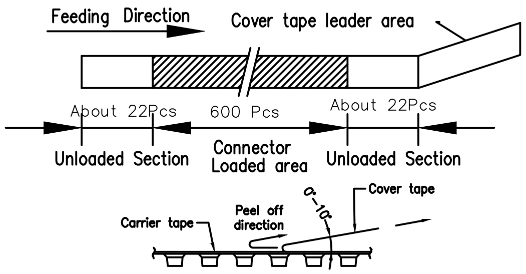
THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	APPROVE BY FRANK	DATE 01/AUG/13	PART NO. FWF25028–SXXS24W5M	ITEM NO. FWF25028
	X.±.012(0.30) | X.°±5°	CHECKED BY CHERRY	DATE 01/AUG/13	TITLE Wire to Board (Wafer) Pitch 2.5mm 180° Vertical (SMT)	TXGA Leader Of Industry
DESIGN UNITS Inch (metric)	X.X±.008(0.20) | .X°±2°				REV 1 | SHEET NO. 2/3
SCALE 5:1 | SIZE A4	X.XX±.006(0.15) | .XX°±1°	DRAWN BY KEVIN	DATE 01/AUG/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
	X.XXX±.004(0.10) | .XXX°±0.5°				

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD



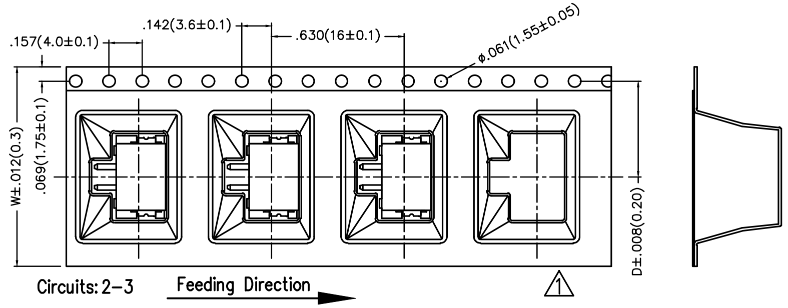


Note:
1. 10 sprocket hole cumulative tolerance±0.2
2. Carrier camber is within 1.0mm in 100mm
3. Materlat: White Conductive polystyrene Alloy 100% recyclable
4. All dimensions meet EIA−481−3 requirements
5. Component load per 13" reel: 600 pcs

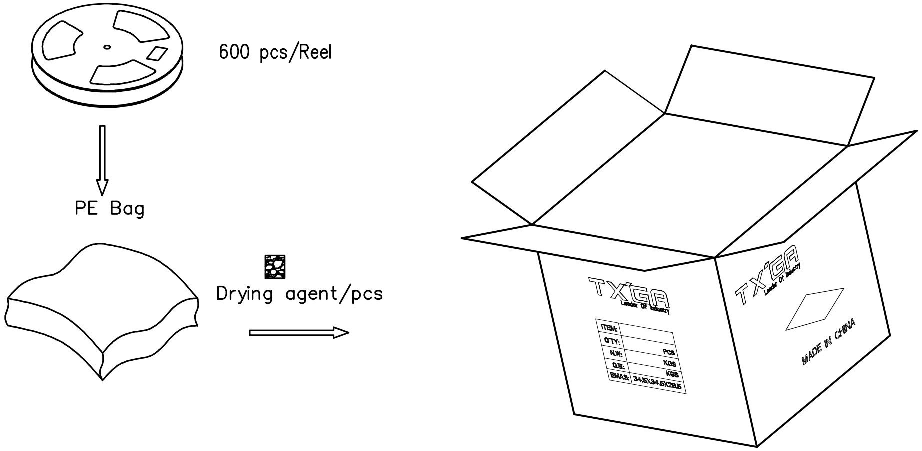


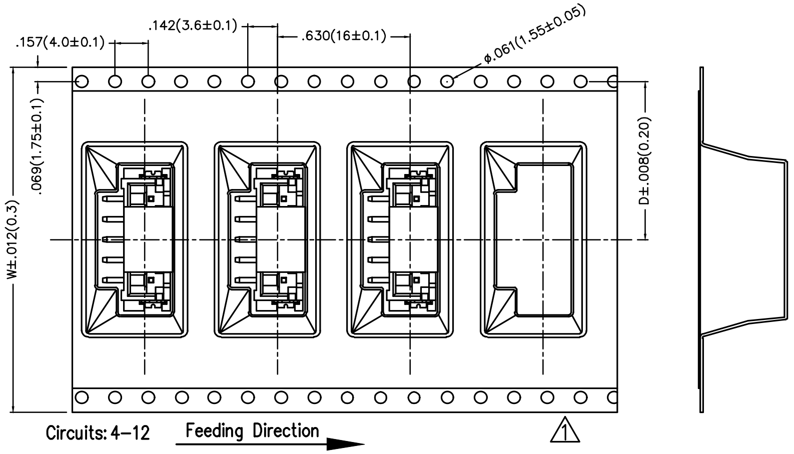
△1

Circuits (n)	Dimensions(in/mm)		Circuits (n)	Dimensions(in/mm)	
	D	W		D	W
2	.453(11.50)	.945(24.00)	8	.795(20.20)	1.732(44.00)
3	.453(11.50)	.945(24.00)	9	.795(20.20)	1.732(44.00)
4	.559(14.20)	1.260(32.00)	10	.795(20.20)	1.732(44.00)
5	.559(14.20)	1.260(32.00)	11	1.031(26.20)	2.205(56.00)
6	.795(20.20)	1.732(44.00)	12	1.031(26.20)	2.205(56.00)
7	.795(20.20)	1.732(44.00)			



Circuits: 2−3





Circuits: 4−12

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 01/AUG/13	PART NO. FWF25028−SXXS24W5M	ITEM NO. FWF25028
	X.±.012(0.30)	X.°±5°	CHECKED BY CHERRY	DATE 01/AUG/13	TITLE Wire to Board (Wafer) Pitch 2.5mm 180° Vertical (SMT)	TXGA Leader Of Industry
DESIGN UNITS Inch (metric)	X.X±.008(0.20)	.X°±2°				REV 1
	X.XX±.006(0.15)	.XX°±1°	DRAWN BY KEVIN	DATE 01/AUG/13		SHEET NO. 3/3
SCALE 5:1 SIZE A4	X.XXX±.004(0.10)	.XXX°±0.5°			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	